

REMARKS

Reconsideration is respectfully requested.

By the above amendment, Applicants have amended independent Claims 1 and 3 to more clearly and specifically claim the subject matter considered to be Applicants' invention, and to provide antecedent basis for "the lower surface" in Claim 3.

It is respectfully submitted that the rejections of Claims 1-5 are improper in that both Leupp et al. and Watanabe et al. fail to teach the required electrical interconnection between the outer conductive surface of the support member and the contact hole in the lower substrate, as is recited in independent Claims 1 and 3.

It is noted that an insulating layer 25 in Leupp et al. (see Column 4, lines 7-11) and layer 8 of Watanabe et al. (see Column 6, lines 16-18) is illustrated and described, and each prevents electrical connection between the upper and lower substrates through the conductive outer layer of the support, thus failing to meet at least that one limitation of Claims 1 and 3.

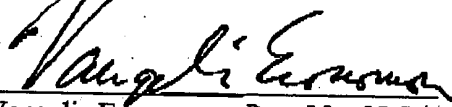
Moreover, even if a reference were to be relied upon that shows such an electrical connection, it would not be obvious to a person of ordinary skill in the art to combine the teaching of that reference to modify either Leupp et al. or Watanabe et al. to achieve the combined recitation of elements in presently pending Claims 1-5. For example, although it may be argued that Fujimori et al. may teach a vertically electrically conducting element (13), there is no disclosure that this teaching should be used to modify the structures of either Leupp et al. or Watanabe et al. in contradiction to their teachings that the support should be electrically isolated. Thus, it would not be obvious to modify a reference against its own teaching as the proposed combination, and it is

respectfully submitted that the rejection is therefore improper. The rejection of Claims 1 and 3 fails to support the disclosure includes a supporting column that joins and provides a uniform cell gap between the upper and lower substrates and also establishes a signal interconnection and also establishes a signal interconnection between the lower substrate and the upper substrate, as recited in Claims 1 and 3.

For the above reasons, it is considered that the claims, as amended, find support in the application specification as filed, and that the combination of elements recited in the pending claims, as amended, distinguish over the references of record. Accordingly, an indication of allowable subject matter is earnestly solicited.

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Respectfully submitted,



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